Yuzhe Fu

No.5, Yiheyuan Road, Haidian District Beijing, P.R.China, 10087

EDUCATION

Peking University - Beijing, China

September 2021 – June 2024

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Email: fuyz@stu.pku.edu.cn

Master in Microelectronics and Solid-State Electronics

GPA: 3.59/4.0

Supervisor: Prof. Hailong Jiao

University of California, Berkeley – Berkeley, USA

August 2019 – December 2019

Global Access ProgramGPA: 3.94/4.0

Southern University of Science and Technology – Shenzhen, China

September 2017 – June 2021

Bachelor of Microelectronics Science and Engineering

- GPA: 3.88/4.0, 1st in Postgraduate Recommendation Evaluation
- Supervisor: Prof. Fengwei An

RESEARCH INTERESTS

- Algorithm-hardware co-design for neural network accelerator
- Energy-efficient and configurable artificial intelligence accelerator design

PROJECT EXPERIENCE

SoftAct: High-Precision Softmax Processing Hardware Unit for Transformer Network with Integrated Nonlinear Activation Function Support

Project Leader

July 2022 – Present

- Developed an enhanced softmax function with penalty, optimizing precision in hardware.
- Introduced sparsity detection for softmax to fully skip redundant operations
- Designed a specialized architecture to implement the proposed techniques and non-linear functions
- SoftAct is synthesized in TSMC 28 nm and simulated based on MobileViT data, attaining peer-leading precision and hardware efficiency
- Wrote a journal paper and planned to submit in August

Nebula: An Energy-Efficient 3D Point Cloud-Based Neural Network Accelerator

Main Contributor & Module Leader

February 2022 – Present

- Responsible for software work (model training, quantization and pruning, algorithm verification, etc.)
- Proposed a novel FPS and its hardware unit, ensuring precision while mitigating complexity
- Implemented data-sensitive analysis and adaptive filter pruning to significantly compress network
- Co-designed a coarse-to-fine-grained data-reuse dataflow scheme, leveraging spatial-temporal locality, block-wise pipelined delay-aggregation, and MLP fusion
- Nebula is fabricated in TSMC HPC 28 nm (In-progress). The simulated effective energy efficiency exceeds 50 TOPS/W
- Co-wrote a conference paper submitted to IEEE/ACM International Conference On Computer Aided Design (ICCAD)

Sagitta: An Energy-Efficient Sparse 3D-CNN Accelerator for Real-Time 3D Understanding Contributor December 2021 – December 2022

- Responsible for pruning and extraction of network data for analysis
- Leveraged locality and small differential value dropout to increase the sparsity of activations
- Co-revised a journal paper submitted to IEEE Internet of Things Journal (IoT-J) (Minor revision)

SGM Accelerator: A 4.29nJ/pixel Stereo-depth Coprocessor with Pixel-level Pipeline and Region-Optimized Semi-Global Matching for IoT Application

Project Leader

February 2020 - June 2021

- Proposed a region-optimized stereo matching strategy improving the speed of traditional semi-global matching algorithm by 5 times while ensuring the accuracy
- Proposed a four-layer parallel pipeline hardware architecture and implemented it on FPGA platform which can extract depth information in real-time at 156MHz and 508fps under VGA resolution

PATENT

• Y. Fu, F. An, et al. (co-inventor), CN Patent, Low-power-consumption stereo matching system and method for acquiring depth information, 2020, CN112070821A

PUBLICATION

- C. Zhou, Y. Fu, M. Liu, S. Qiu, G. Li, Y. He, and H. Jiao, "An Energy-Efficient 3D Point Cloud Neural Network Accelerator with Efficient Filter Pruning, MLP Fusion, and Dual-Stream Sampling," IEEE/ACM International Conference On Computer Aided Design (ICCAD), 2023, under review.
- C. Zhou, M. Liu, S. Qiu, X. Cao, <u>Y. Fu</u>, Y. He, and H. Jiao, "Sagitta: An Energy-Efficient Sparse 3D-CNN Accelerator for Real-Time 3D Understanding," *IEEE Internet of Things Journal (IoT-J)*, 2023, under review (minor revision).
- P. Dong, Z. Chen, Z. Li, <u>Y. Fu</u>, L. Chen, F. An, "A 4.29nJ/pixel Stereo-depth Coprocessor with Pixel-level Pipeline and Region-Optimized Semi-Global Matching for IoT Application," IEEE Transactions on Circuits and Systems I: Regular Papers (TCAS-I), 2021.

TAPE OUT

 An energy-efficient pipelined and configurable 3D point cloud-based neural network accelerator is being designed in TSMC 28-nm HPC technology with an area of 2.0 mm×1.5 mm and is expected to be taped out in July 2023

HONORS & AWARDS

- Excellent Graduate Award, Southern University of Science and Technology, 2021
- China National Scholarship, Ministry of Education of the PRC, 2020
- First Class Scholarship, Southern University of Science and Technology, 2019
- First Class Scholarship, Southern University of Science and Technology, 2018
- Third Class Freshman Scholarship, Southern University of Science and Technology, 2017

SKILLS

- English: TOFEL 104
- Proficient in digital integrated circuit (IC) front-end development and logic synthesis, FPGA development and board-level verification, and neural network model compression
- Familiarity with the following tools: Cadence (Genus and NCSim), Vivado; Verilog HDL, PyTorch, Intel Distiller (Model Compression)
- Knowledgeable in Python, JAVA, MATLAB, Shell, Makefile
- You can find more information through my homepage: https://vuzhe-fu.github.jo